SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

- UBT™ (Universal Bus Transceiver)
 Combines D-Type Latches and D-Type
 Flip-Flops for Operation in Transparent,
 Latched, Clocked, or Clock-Enabled Mode
- State-of-the-Art Advanced BiCMOS
 Technology (ABT) Widebus™ Design for
 2.5-V and 3.3-V Operation and Low
 Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- High-Drive (-24/24 mA at 2.5-V and -32/64 mA at 3.3-V V_{CC})
- I_{off} and Power-Up 3-State Support Hot Insertion
- Use Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- Auto3-State Eliminates Bus Current Loading When Output Exceeds V_{CC} + 0.5 V
- Flow-Through Architecture Facilitates
 Printed Circuit Board Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

NOTE: For tape and reel order entry:

The DGGR package is abbreviated to GR and the DGVR package is abbreviated to VR.

description

The 'ALVTH16601 devices are 18-bit universal bus transceivers designed for 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The devices combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.



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TEXAS INSTRUMENTS

SN54ALVTH16601 . . . WD PACKAGE SN74ALVTH16601 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)

OEAB [₁ U	56	CLKENAB
LEAB [2	55	CLKAB
A1 [3	54	B1
GND [4	53	GND
A2 [5	52	B2
А3 [6	51] B3
v _{cc} [7	50] v _{cc}
A4 [8	49	B4
A5 [9	48	B5
A6 [47	B6
GND [11	46	GND
A7 [12	45	
A8 [13	44] B8
A9 [14	43] B9
A10 [15	42	B10
A11 [16	41	B11
A12 [17	40	B12
GND [18	39	GND
A13 [19	38	B13
A14 [20	37	B14
A15 [21	36	B15
v _{cc} [22	35] v _{cc}
A16 [23	34	B16
A17 [24	33] B17
GND [25	32] GND
A18 [26	31	B18
OEBA [27	30] CLKBA
LEBA [28	29	CLKENBA

SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

description (continued)

Data flow in each direction is controlled by output-enable (\overline{OEAB} and \overline{OEBA}), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output enable \overline{OEAB} is active low. When \overline{OEAB} is low, the outputs are active. When \overline{OEAB} is high, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, CLKBA, and CLKENBA.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ALVTH16601 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALVTH16601 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

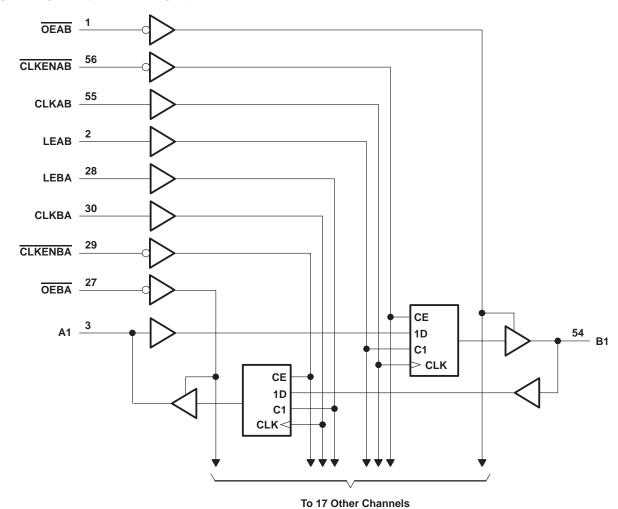
	I	NPUTS			OUTPUT
CLKENAB	OEAB	LEAB	CLKAB	Α	В
Х	Н	Χ	Χ	Χ	Z
Х	L	Н	Χ	L	L
Х	L	Н	Χ	Н	Н
н	L	L	Χ	Χ	в ₀ ‡
н	L	L	Χ	Χ	в ₀ ‡ в ₀ ‡
L	L	L	\uparrow	L	L
L	L	L	\uparrow	Н	Н
L	L	L	L or H	X	в ₀ ‡

[†] A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, CLKBA, and CLKENBA.



[‡] Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)





SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.5 V to 4	.6 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high or power-off state, V _O (see Note 1)0.5 V to	7 V
Output current in the low state, IO: SN54ALVTH16601	mA.
SN74ALVTH16601 128	mA
Output current in the high state, IO: SN54ALVTH16601 –48	mΑ
SN74ALVTH16601 –64	· mA
Input clamp current, I _{IK} (V _I < 0)	mA
Output clamp current, I_{OK} ($V_O < 0$)	mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	
DGV package 86°0	
DL package	C/W
Storage temperature range, T _{stg} 65°C to 15	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions, V_{CC} = 2.5 V \pm 0.2 V (see Note 3)

			SN54ALVTH16601			SN74ALVTH16601			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage	Supply voltage			2.7	2.3		2.7	V
VIH	High-level input voltage		1.7	2		1.7			V
V _{IL}	Low-level input voltage			Š	0.7			0.7	V
VI	Input voltage		0	Vcc	5.5	0	VCC	5.5	V
loн	High-level output current			7	-6			-8	mA
lai	Low-level output current			2	6			8	mA
lOL	Low-level output current; current duty cycle ≤	50%; f≥1 kHz	20,00	5	18			24	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q		10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 3.3 V \pm 0.3 V (see Note 3)

			SN54	ALVTH1	6601	SN74ALVTH16601			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vcc	Supply voltage		3		3.6	3		3.6	V
VIH	High-level input voltage		2		1/2	2			V
V _{IL}	Low-level input voltage			Š	0.8			0.8	V
VI	Input voltage		0	VCC	5.5	0	VCC	5.5	V
IOH	High-level output current			1	-24			-32	mA
la	Low-level output current			2	24			32	mA
lor	Low-level output current; current duty cycle ≤	50%; f≥1 kHz	20,	5	48			64	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q		10			10	ns/V
Δt/ΔVCC	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

DA	RAMETER	TEST CO	NUDITIONS	SN54	ALVTH1	6601	SN74	ALVTH1	6601	UNIT
PA	RAWETER	1251 00	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 2.3 V,	I _I = -18 mA			-1.2			-1.2	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2		
Vон		V _{CC} = 2.3 V	$I_{OH} = -6 \text{ mA}$	1.8						V
		VCC = 2.3 V	$I_{OH} = -8 \text{ mA}$				1.8			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	$I_{OL} = 100 \mu\text{A}$			0.2			0.2	
			I _{OL} = 6 mA			0.4				
VOL		V _{CC} = 2.3 V	I _{OL} = 8 mA						0.4	V
		VCC = 2.3 V	I _{OL} = 18 mA			0.5				
			I _{OL} = 24 mA						0.5	
V _{RST} ‡		V _{CC} = 2.7 V	$I_O = 1 \text{ mA},$ $V_I = V_{CC} \text{ or GND}$			0.55			0.55	V
Con	Control inputs	$V_{CC} = 2.7 \text{ V},$	$V_I = V_{CC}$ or GND		- 3	±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 2.7 \text{ V},$	V _I = 5.5 V		24	10			10	μА
Ιį	A or B ports	V _{CC} = 2.7 V	V _I = 5.5 V		7	10			10	
			$V_I = V_{CC}$		2	1			1	
			V _I = 0		5	- 5			– 5	
I _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V	Q					±100	μΑ
I _{BHL} §		$V_{CC} = 2.3 \text{ V},$	V _I = 0.7 V		115			115		μΑ
IBHH		$V_{CC} = 2.3 \text{ V},$	V _I = 1.7 V		-10			-10		μΑ
IBHLO#	#	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	300			300			μΑ
Івнно	I	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	-300			-300			μΑ
lEX☆		$V_{CC} = 2.3 \text{ V},$	$V_0 = 5.5 \text{ V}$			125			125	μΑ
I _{OZ(PU}	/PD)□	$V_{CC} \le 1.2 \text{ V}, V_O = \underline{0.5} \text{ V}$ $V_I = \text{GND or } V_{CC}, \overline{\text{OE}} =$	to V _{CC} , don't care			±100			±100	μА
		V _{CC} = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1	
ICC		IO = 0,	Outputs low		2.5	4.5		2.5	4.5	mA
			Outputs disabled		0.04	0.1		0.04	0.1	
Ci		V _{CC} = 2.5 V,	V _I = 2.5 V or 0		3			3		pF
C _{io}		$V_{CC} = 2.5 \text{ V},$	V _O = 2.5 V or 0		7			7		pF

[†] All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Data must not be loaded into the flip-flops/latches after applying power.

[§] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[#] An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least IBHHO to switch this node from high to low.

[☆]Current into an output in the high state when V_O > V_{CC}

[□] High-impedance state during power up or power down

SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

D/	ARAMETER	TEST (CONDITIONS	SN54	ALVTH1	6601	SN74	ALVTH1	6601	UNIT	
F#	AKAWETEK	lE31 C	CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
٧ıK		$V_{CC} = 3 V$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	$I_{OH} = -100 \mu A$	V _{CC} -0	.2		V _{CC} -0.	.2			
Vон		V _{CC} = 3 V	$I_{OH} = -24 \text{ mA}$	2						V	
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2				
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OL} = 100 μA			0.2			0.2		
			$I_{OL} = 16 \text{ mA}$						0.4		
VOL			$I_{OL} = 24 \text{ mA}$			0.5					
VOL		VCC = 3 V	$I_{OL} = 32 \text{ mA}$						0.5	V	
			$I_{OL} = 48 \text{ mA}$			0.55					
			$I_{OL} = 64 \text{ mA}$						0.55		
V _{RST}	‡	V _{CC} = 3.6 V	$I_O = 1 \text{ mA},$ $V_I = V_{CC} \text{ or GND}$		Š	0.55			0.55	V	
	Control innuts	V _{CC} = 3.6 V,	V _I = V _{CC} or GND		24	±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		7	10			10		
II			V _I = 5.5 V		2	10			10	μΑ	
	A or B ports	V _{CC} = 3.6 V	$V_I = V_{CC}$	Ć	3	1			1		
			V _I = 0	Q		- 5			– 5		
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ	
I _{BHL} §		$V_{CC} = 3 V$,	V _I = 0.8 V	75			75			μΑ	
IBHH		$V_{CC} = 3 V$,	V _I = 2 V	-75			-75			μΑ	
IBHLO	,#	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	500			500			μΑ	
Івнно)	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	-500			-500			μΑ	
lEX☆		$V_{CC} = 3 V$	$V_0 = 5.5 \text{ V}$			125			125	μΑ	
I _{OZ(Pl}	U/PD)□	$V_{CC} \le 1.2 \text{ V}, V_{O} = \frac{0.5}{\text{OE}}$ $V_{I} = \text{GND or } V_{CC}, \overline{\text{OE}}$	V to V _{CC} , = don't care			±100			±100	μΑ	
		V _{CC} = 3.6 V,	Outputs high		0.06	0.1		0.06	0.1		
ICC		$I_{O} = 0$,	Outputs low		3.5	5		3.5	5	mA	
		LV V STONE	Outputs disabled		0.06	0.1		0.06	0.1		
∆ICC◊		$V_{CC} = 3 \text{ V to } 3.6 \text{ V, On}$ Other inputs at V_{CC} or	e input at V _{CC} – 0.6 V, GND			0.4			0.4	mA	
Ci		$V_{CC} = 3.3 \text{ V},$	$V_{I} = 3.3 \text{ V or } 0$		3			3		pF	
Cio		V _{CC} = 3.3 V,	V _O = 3.3 V or 0		7			7		pF	
				-				-			

 $[\]uparrow$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



[‡] Data must not be loaded into the flip-flops/latches after applying power.

[§] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[#] An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least IBHHO to switch this node from high to low.

 $[\]star$ Current into an output in the high state when $V_O > V_{CC}$

[□] High-impedance state during power up or power down

[♦] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

				SN54ALVTI	H16601	SN74ALVT	H16601	LINUT	
				MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency				150		150	MHz	
	Pulse duration	LE high		1.8		1.8		20	
t _W	Pulse duration	CLK high or low		2.3		2.3		ns	
		A B h - (OL)(^	Data high	4		4			
		A or B before CLK↑	Data low	5.2		5.2		ns	
	Catura tima	A or B before LE↓	CLK high	0.7	EN	0.7			
t _{su}	Setup time		CLK low	0.9	14	0.9			
1	J Setup time		Data high	1.7,0		1.7			
		CLKEN before CLK↑	Data low	2.3		MIN MAX 0 150 1.8 2.3 4 5.2 0.7 0.9			
		A B - 4 O K^	Data high	0.5		0.5			
		A or B after CLK↑	Data low	0.5		0.5			
		A an D affan I E l	CLK high	2.3		2.3			
th	Hold time	A or B after LE↓	CLK low	2.4		2.4		ns	
			Data high	0.5		0.5		[
		CLKEN after CLK↑	Data low	0.5		0.5			

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

				SN54ALVT	H16601	SN74ALVT	H16601	UNIT
				MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency				150		150	MHz
	Dulas direction	LE high		1.8		1.8		
t _W	Pulse duration	CLK high or low		2.3		2.3		ns
		A B b (OLIK)	Data high	2.4		2.4		
		A or B before CLK	Data low	3.8		3.8		ns
١.	Catua tima	A or B before LE↓	CLK high	1	EN	1		
^t su	t _{SU} Setup time		CLK low	0.6	Ty.	0.6		
			Data high	1.4,0		1.4		
		CLKEN before CLK	NIN 1.8 2.3 2.4 Data high 2.4 Data low 3.8 CLK high 1 CLK low 0.6 Data high Data low 1.9 Data high Data low 0.5 CLK high 2 CLK low 2.3 Data high 0.6 Data high 0.6 CLK low 2.3 Data high 0.6 CLK low 0.6 CLK		1.9			
		A B (1 OL 1/4)	Data high	0.5		0.5		
		A or B after CLK	Data low	0.5		0.5		ns
1.	Hald time	A an D after I E	CLK high	2		2		
th	Hold time	A or B aπer LE↓	CLK low	2.3		2.3		
		OLIVEN - fra - OLIV	Data high	0.6		0.6		
		A or B before CLK↑ A or B before LE↓ CLKEN before CLK↑ A or B after CLK↑ A or B after LE↓ CLKEN after CLK↑	Data low	0.5		0.5		

SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

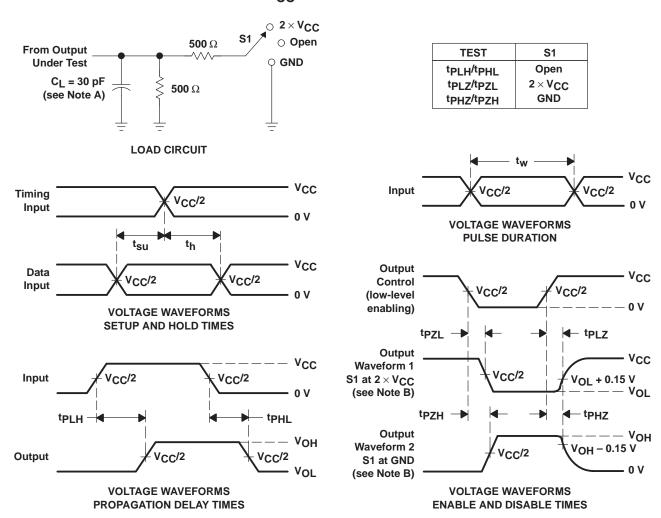
PARAMETER	FROM	то	SN54ALV	ГН16601	SN74ALVT	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
f _{max}			150		150		MHz
t _{PLH}	B or A	A or B	1.1	<u>4</u> .1	1.1	4.1	ns
t _{PHL}	D 01 A	A or B	1.6	4.8	1.6	4.8	115
^t PLH	LEBA or LEAB	A or B	2.1	5	2.1	5	ns
^t PHL	LEDA OI LEAD	AOID	2.4	5.4	2.4	5.4	115
^t PLH	CLKBA or CLKAB	LKAB A or B	2	5	2	5	ns
t _{PHL}	CLNBA OF CLNAB		2.5	5.9	2.5	5.9	115
^t PZH	OEBA or OEAB	A or B	1.2	4.8	1.2	4.8	ns
tpzL	OEBA OF OEAB	AUID	1	4.6	1	4.6	115
^t PHZ	OEBA or OEAB	A or B	1.2	5.2	1.2	5.2	ns
t _{PLZ}	OEBA OI OEAB	AOID	1	3.9	1	3.9	113

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	SN54ALV	TH16601	SN74ALVT	H16601	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
f _{max}			150		150		MHz
t _{PLH}	D A	A or B	1.4	3 .9	1.4	3.9	20
t _{PHL}	B or A	A or B	1.1	3.9	1.1	3.9	ns
t _{PLH}	LEDA an LEAD	A or B	2	4.6	2	4.6	ns
t _{PHL}	LEBA or LEAB	AOID	2.1	4.6	2.1	4.6	115
^t PLH	CLKBA or CLKAB	A or B	1.9	4.5	1.9	4.5	ns
^t PHL	CLNDA OI CLNAD	AOIB	2.2	4.6	2.2	4.6	115
^t PZH	OEBA or OEAB	A or B	Q 1	4.2	1	4.2	ns
t _{PZL}	OEBA OF OEAB	AUID	1	4.4	1	4.4	110
^t PHZ	OEBA or OEAB	A or B	1.8	5.3	1.8	5.3	ns
t _{PLZ}	OEDA OF OEAB	AUID	1.7	4.6	1.7	4.6	110

SCES143A - SEPTEMBER 1998 - REVISED JULY 1999

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



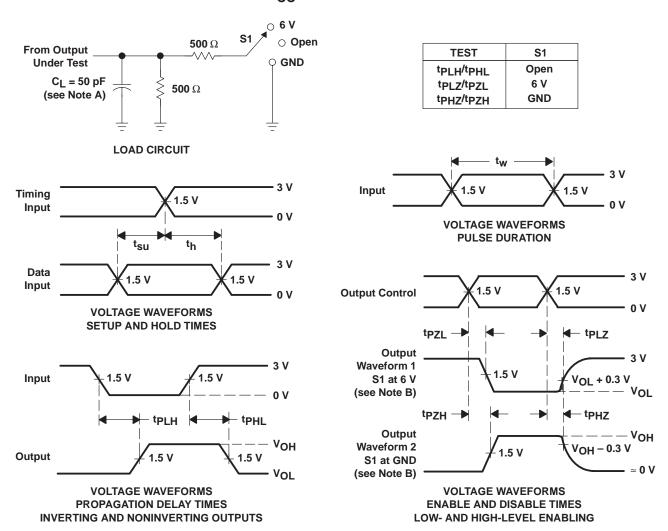
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2$ ns, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform22 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

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